FAIRCHILD SEMICONDUCTOR

IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, Feb 22, 2014 01:46 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
1N4736A_T50R	1N4736A_T50R	DO-41 (Glass)			SUBCONTRACTOR	**0.324186**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	Other	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom

RoHS Directive 2011/65/EU	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

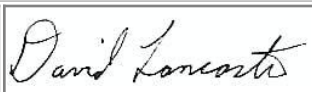
Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU
7(c)-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g piezoelectronic dev

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DO-41 (Glass)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
CSS Wire	Other Ferrous alloys, non-stainless steels	202.316	Supplier		Carbon	1.010	7440-44-0	3116
			Supplier		Copper	70.700	7440-50-8	218085
			Supplier		Iron	130.000	7439-89-6	401005
			Supplier		Manganese	0.404	7439-96-5	1246
			Supplier		Phosphorus	0.101	7723-14-0	312
			Supplier		Sulfur	0.101	7704-34-9	312
Chip	Other inorganic materials	0.093	Supplier		Silicon	0.093	7440-21-3	285
Dumet Wire	Other Ferrous alloys, non-stainless steels	57.927	Supplier		Cobalt	0.290	7440-48-4	895
			Supplier		Iron	32.700	7439-89-6	100868
			Supplier		Manganese	0.463	7439-96-5	1428
			B	Nickel (external applications only)	Nickel	24.300	7440-02-0	74957
			Supplier		Silicon	0.174	7440-21-3	537
Encapsulation	Ceramics / Glass	60.330	Supplier		Diboron Trioxide *	1.510	1303-86-2	4658
			A	Lead/Lead Compounds	Lead (II,IV) oxide	36.500	1314-41-6	112590
			Supplier		Potassium Oxide	2.420	12136-45-7	7465
			Supplier		Silicon Dioxide, quartz	19.900	14808-60-7	61385
Plating	Other Nonferrous metals & alloys	3.520	Supplier		Tin	3.520	7440-31-5	10858